Texas Instruments Inc. (DUNS# 00-732-1904)
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Distribute - RoHS and IEC 62474 DB
06/09/2022

### Details for "TLV70033DSET"

## **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV70033DSET	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DSE   6	1.5x1.5x0.75	4.1

### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

## **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000002	0.006685	67	0.000049	0
Precious Metals	Gold	7440-57-5	0.029914	99.993315	999933	0.727338	7273
Sub-Total			0.029916	100	1000000	0.727387	7274
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.011773	29.998726	299987	0.286252	2863
Other Inorganic Materials	Silica	7631-86-9	0.001766	4.499936	44999	0.042939	429
Other Organic Materials	Chlorine	7782-50-5	0.000014	0.035673	357	0.00034	3
Thermoplastics	Ероху	85954-11-6	0.025692	65.465664	654657	0.624683	6247
Sub-Total			0.039245	100	1000000	0.954215	9542
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1.462995	97.533	975330	35.571708	355717
Copper and Its Alloys	Iron	7439-89-6	0.034755	2.317	23170	0.845044	8450
Copper and Its Alloys	Phosphorus	7723-14-0	0.000375	0.025	250	0.009118	91
Zinc and Its Alloys	Zinc	7440-66-6	0.001875	0.125	1250	0.045589	456
Sub-Total			1.5	100	1000000	36.471459	364715
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	2.312777	23128
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.018965	190
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.099689	997
Sub-Total			0.1	100	1000000	2.431431	24314
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	1.981474	90.500001	905000	48.178166	481782
Other Plastics and Rubber	Carbon Black	1333-86-4	0.010947	0.499983	5000	0.266169	2662
Thermoplastics	Ероху	85954-11-6	0.197053	9.000016	90000	4.791207	47912
Sub-Total			2.189474	100	1000000	53.235541	532355
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.25417	100	1000000	6.179967	61800
Sub-Total			0.25417	100	1000000	6.179967	61800
Total			4.112805			100	1000000

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. <u>See Glossary of Terms for more details</u>.

# Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

# **Product Content Methodology**

For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

# Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

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Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.